

IN THE SPECIFICATION:

Please amend the paragraph beginning on page 5, line 23, as follows:

According to a further aspect of the invention there, is provided a device manufacturing method including providing a substrate that is at least partially covered by a layer of radiation-sensitive material; projecting a patterned beam of radiation onto a target ~~portion~~ portion of the layer of radiation-sensitive material, wherein providing the substrate includes clamping the substrate to a plate member having a larger nominal size than the substrate and loading the plate member having the substrate clamped thereto into the lithographic apparatus.

Please amend the paragraph beginning on page 10, line 10, as follows:

As can be seen from Figure 3, the height T of the ~~clamp~~ clamp ring 15 will obstruct the projection beam PB if it is attempted to project an image within a distance d_1 of the inner periphery of the clamp ring. The exact value of distance d_1 will depend on the thickness T and the numeric aperture (NA) of the projection lens PL, which determines the angle of the outermost rays of the projection beam. The width of the annulus that cannot be imaged on will be equal to d_1 plus the maximum width O_{max} of the overlap between clamp ring 15 and wafer W. By suitable choice of T and O_{max} , the width of the unimageable portion of the substrate, which may be regarded as the shadow S_1 of the clamp ring to the projection beam, can be made comparable to the normal edge bead of 3mm. In a lithographic apparatus with on-axis leveling, the leveling sensor beam LS-B will have a ~~sallower~~ shallower angle of inclination than the projection beam. This means that the shadow S_{LB} of the clamp ring to the leveling sensor beam LS-B will be wider and the vertical position of a larger portion of the wafer surface cannot be measured. This problem can be avoided by extrapolating from leveling measurements made in the inner portion of the substrate W. In Figure 4, the ~~imigable~~ imageable area is shown cross-hatched and the boundary of the shadow of the level sensor beam is shown as a dashed line.